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cont.

- (d) depositing a fourth layer on the previous layers;
 - (e) etching the fourth layer to obtain the sloped support; and
 - (f) removing the second layer to obtain the suspended microstructure with the sloped support.
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4. (Amended) A method according to claim 1, further comprising, after step (e) and before step (f), steps of:

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- (i) depositing a fifth planarization layer for covering the previous layers except for a top portion of the sloped support;
 - (ii) depositing a sixth layer on the previous layers; and
 - (iii) etching the sixth layer to obtain a suspended microplatform;
- wherein step (f) further includes a removal of the fifth layer.
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15. (Amended) A method according to claim 14, wherein the polymer is polyimide.
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